Dispersant

TG Parikku II

TG Parikku II is a plastically fluidizing material that is known to be effective on clay having acuity in particular such as a high N value and high tackiness. The characteristics of ground formed of viscous soil that is subject to excavation using the pressurized mud and soil shielding method vary depending on the region. TG Parikku II is an innovative dispersant capable of exhibiting in a low concentration range, in relation to viscosity due to electrical elements obtained from mechanical resistance applied in the past during the stages when the ground layers were configured, the effects of such as reducing friction due to low mechanical resistance in the discharge process rather than excavation and preventing separation due to a self-standing property.

In performing the muddy water shielding method, TG Parikku II has the effect of lowering viscosity against the significant increase of viscosity of muddy water upon column excavation of silt and clay layers and is capable of reducing the volume of excess muddy water for treatment.

Features of TG Parikku II

- 1. In the fluid transportation process of such as the pressurized mud and soil shielding and fluidization treatment methods, the dispersing effect of TG Parikku II promotes fluidity.
- 2. TG Parikku II has excellent effects of realizing separation and preventing adhesion which in turn prevents clogging of the chamber and the increase of torque pressure for the cutter during ground excavation of viscous soil having a high N value and high tackiness.
- 3. As TG Parikku II has an excellent dispersing effect, this makes is possible to lower the injection rate and suppress the volume of discharged mud. By combining use with TG Gel as a supplementary agent, it is possible to prevent the excavated soil from returning to muddy water and enables reform into good quality excavated soil that is not loose.
- 4. As TG Parikku has an excellent effect of preventing adhesion, it is also optimal for pressurized pumping sites (when excavating viscous soil).
- 5. Even in the process of injection with such as the fluidization treatment method, TG Parikku is optimal for its effects of suppressing solidified bonding and promoting fluidity.
- 6. TG Parikku has the effect of lowering viscosity against the increase of viscosity of muddy water when performing the muddy water shielding method and is capable of reducing the volume of excess muddy water for treatment.

Property Specifications of TG Parikku II

Appearance: Grayish white powder

pH: 8.0 ± 1.5 (0.2% solution) Bulk specific gravity: 1.05 ± 0.05

Packaging: 20 kg bag, 1 t bag, 10 t jet pack truck

Additive Amount of TG Parikku II upon Excavation with Pressurized Mud and Soil Shielding

TG Parikku II $3.0 - 10.0 \text{ kg/m}^3$

TG Jeru $1.0 - 2.0 \text{ kg/m}^3$

Example of Use on Clod with a High N Value



TG Parikku II Used Independently

Capable of dispersing clod with a low injection rate



TG Parikku II + TG Gel Used Together

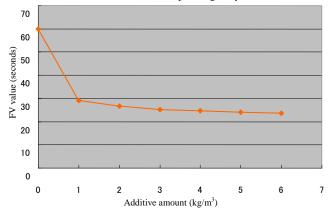
Capable of being reformed into discharge soil of good quality without extremely becoming muddy water

TG Parikku II Viscosity Lowering Effect

Effect of lowering viscosity of muddy water

(Properties of Muddy Water)

FV value: 60 seconds, Specific gravity: 1.22



Viscosity lowering effect when mixed in cement

	Cement	TG Parikku II	РН	FV value
No.	(kg/m^3)	(kg/m^3)		(seconds)
1	0	0	7.5	32±1
2	8	0	8.5	102±1
3	8	5	8.5	30±1
4		6	8.5	27±1

Technica Goudou Co., Ltd. (Head Office) 12th Floor, Higashi Kobe Center Bldg. 8-6-26 Motoyama-Minamimachi, Higashi Nada-ku, Kobe, Hyogo 658-0015 Phone: 81-78-436-0280 / Fax: 81-78-451-0257 (Tokyo Sales Office) 1st Floor, Ikebukuro FN Bldg. 3-9-10 Higashi Ikebukuro, Toshima-ku, Tokyo 170-0013 Phone: 81-3-6907-2566 / Fax: 81-3-3985-8611 (Sendai Sales Office) 9th Floor, Izumi Chuo Bldg. 1-16-6 Izumi Chuo, Izumi-ku, Sendai, Miyagi 981-3133 Phone: 81-22-375-3981 / Fax: 81-22-375-3983 (Kobe Laboratory) Complex D, Room 405 1-2-25 Wadayamadori, Hyogo-ku, Kobe, Hyogo 652-0884 Phone/Fax: 81-78-671-1190 Website: http://www.technica-goudou.co.jp/